

- 规格书 -

产品型号：MBR-16-WK (thin)

产品名称：旋转编码开关

SM SWITCH CO.,LTD

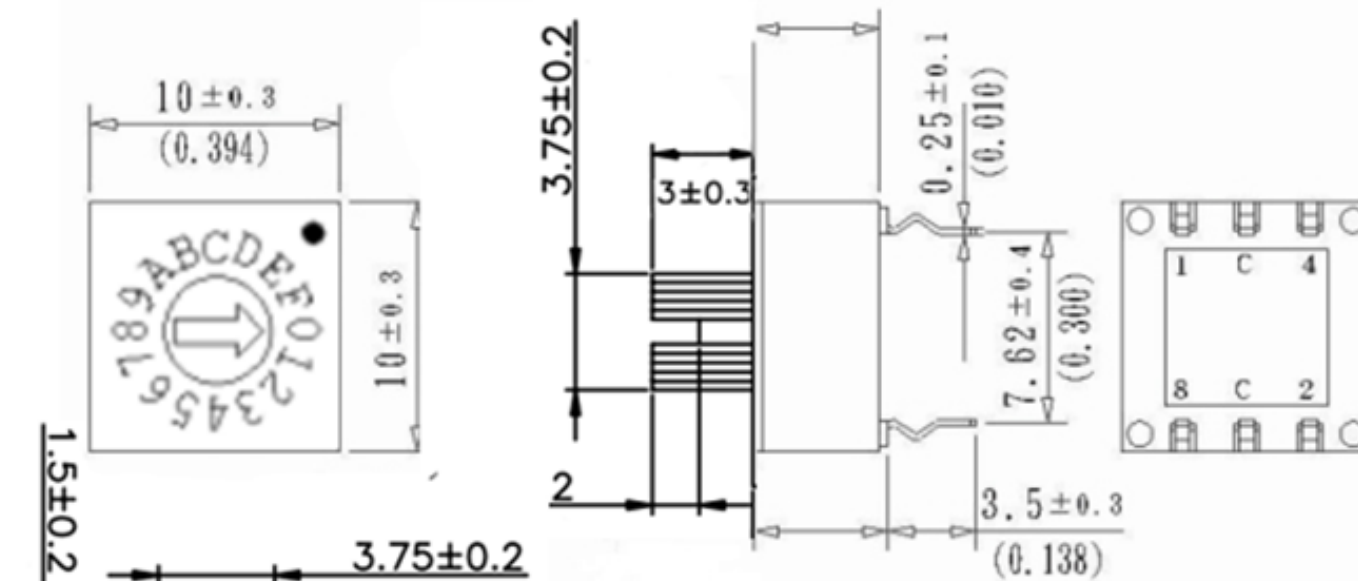
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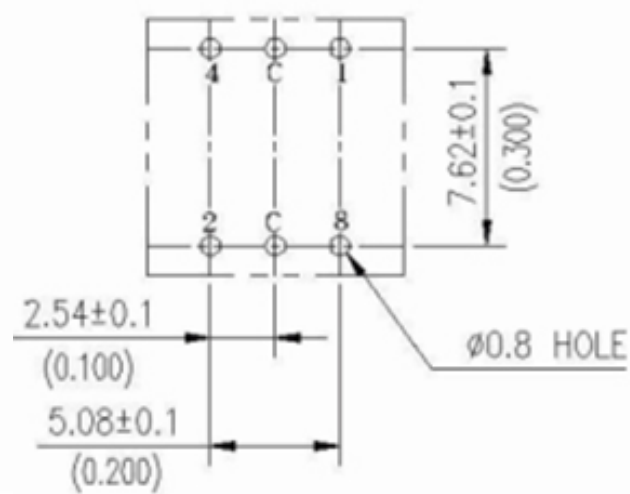
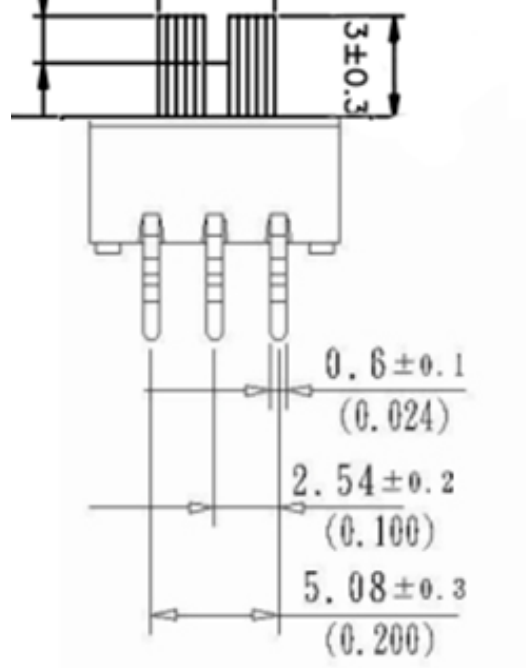
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MARK	DATE	REMARKS
△		
△		



P. C. B LAYOUT
(TOP VIEW)
ERDxxxxS



		Reel Code				
		C	1	2	4	8
10 P o s i t i o n	0	●				
	1	●	●			
	2	●		●		
	3	●	●	●		
	4	●			●	
	5	●	●		●	
	6	●		●	●	
	7	●	●	●	●	
	8	●				●
	9	●	●			●
16 P o s i t i o n	A	●		●		●
	B	●	●	●		●
	C	●			●	●
	D	●	●		●	●
	E	●		●	●	●
	F	●	●	●	●	●

APPD	CHKD	D'SGD	TITLE	ROTARY DIP SWITCH	
YD WANG	J.S KIM	H.S LEE	MODEL NO.	MBR-16-WK (thin)	REV A
			SM SWITCH CO., LTD.		



ROTARY DIP SWITCH SPECIFICATION

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1. Style:

This specification describes "Rotary Switch" mainly used as signal switch of electric devices with the general requirements of mechanical and electrical characteristics.

1.1 Operating / Storage Temperature Range : -40°C ~ +85°C

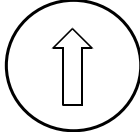
2. Current Range:

2.1 None-Switching : 200 mA, 42V

2.2 Switching : 150 mA, 42V

3. Type of Actuation : Rotating

4. Test Sequence :

ELECTRICAL PERFORMANCE	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
	1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product
	2	Contact Resistance	① To be measured between the two terminals associated with each switch pole ② Measurements shall be made with a 1kHz shall current contact resistance meter	80mΩ max.(initial)
	3	Insulation Resistance	250V DC, 1minute ±5seconds	100MΩ min
	4	Dielectric withstanding Volotage	250V AC(50Hz or 60Hz)shall be applied between all the adjacent terminal and between the terminal and the frame For 1 minute	There shall be no breakdown or flashover
5	Operation Force	Applied in the direction of operation 	700gf/cm. max	



ROTARY DIP SWITCH SPECIFICATION

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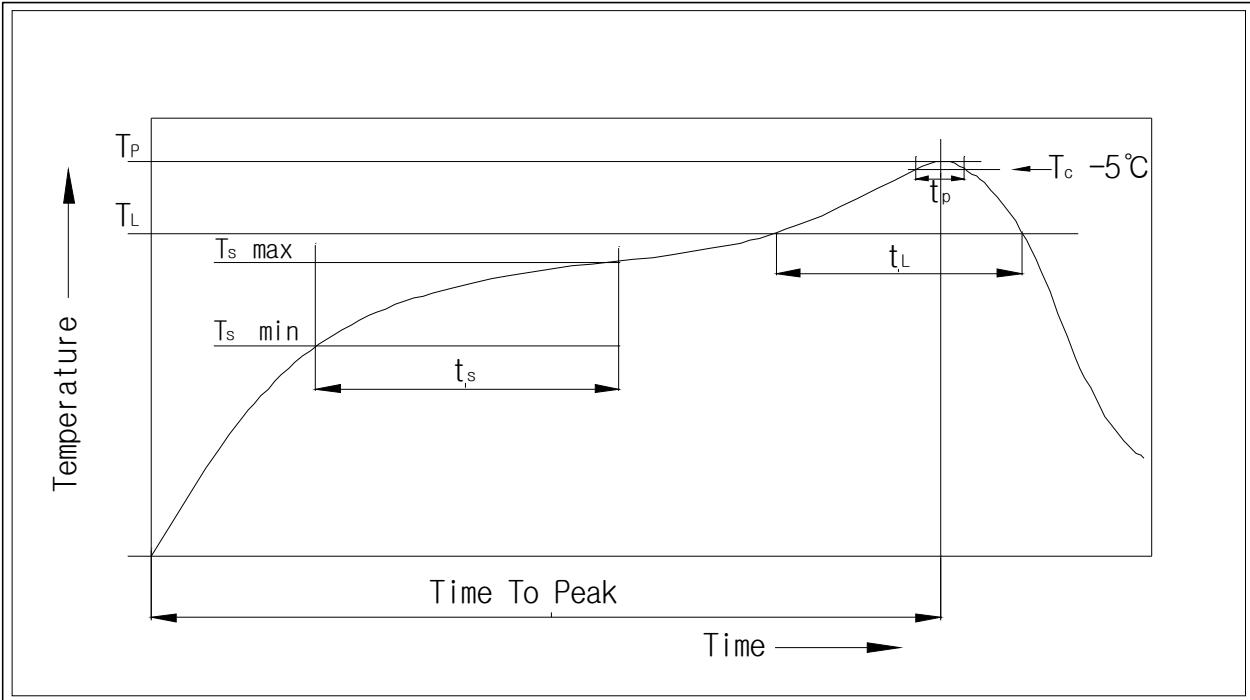
M A C H I N P E R F O R M A N C E	6	Operation Life	<p>Measurements shall be made following the test set forth below:</p> <p>1)150mA, 42V DC resistive load 2)Rate of operation: 15~20 cycles/ minute 3)Step of operation: 10,000 steps</p>	<p>1)As shown in item 3,4 2)Contact Resistance: 200mΩ max 3)Final-after test</p>
	7	Resistance Low Temperature	<p>Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made:</p> <p>1)Temperature: -60℃ ±3℃ 2)Time: 96 hours</p>	<p>1)As shown in item 3~5 2)Contact Resistance: 200mΩ max</p>
	8	Resistance High Temperature	<p>Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made:</p> <p>1)Temperature: 125℃ ±2℃ 2)Time: 96 hours</p>	<p>1)As shown in item 3~5 2)Contact Resistance: 200mΩ max</p>
	9	Resistance Humidity	<p>Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made:</p> <p>1)Temperature: 40℃ ±2℃ 2)Relative humidity: 90~95% 3)Time: 96 hours</p>	<p>1)As shown in item 4 2)Contact Resistance: 200mΩ max 3)Insulation Resistance: 10MΩ min</p>



ROTARY DIP SWITCH SPECIFICATION

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6. Reflow Soldering Conditions:



1) Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Average Ramp-UP Rate($T_{s \text{ max}}$ to T_P)	3°C/second max
Preheat - Temperature Min($T_{s \text{ min}}$) - Temperature Max($T_{s \text{ max}}$) - Time ($t_{s \text{ min}}$ to $t_{s \text{ max}}$)	150°C 200°C 60-100seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	217°C 60-100seconds
Peak/Classification Temperature(T_P)	240~260°C +0°C/ -5°C
Time within 5°C of actual Peak Temperature(t_p)	min 30 seconds
Ramp-Down Rate	6°C/sec max
Reflow Soldering	260°C/4~5 seconds max

7. This item is "ROHS" Compliant



ROTARY DIP SWITCH SPECIFICATION

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8. Part List

NO	PART NAME	Q'TY	MATERIALS	TREATMENT	REMARK
1	COVER	1	PA9T		
2	BASE	1			
3	ACTUATOR	1	PA9T		
4	CONTACT & TERMINAL	1	PHOSPHOR BRONZE	CONTACT AND TERMINAL PLATING: GOLD PLATING OVER NICKEL TINNING	Au 0.03 μ m Min Ni 0.1 μ m Min TIN 0.1 μ m Min
5	PCB	1	EPOXY	PLATING: GOLD PLATING	Au 0.05 μ m Min
6	O-Ring	1	SILICONE		